

200G 1300 km & 100G 3000 km CFP Coherent (OM8668XX100)

Databrief

Product Features

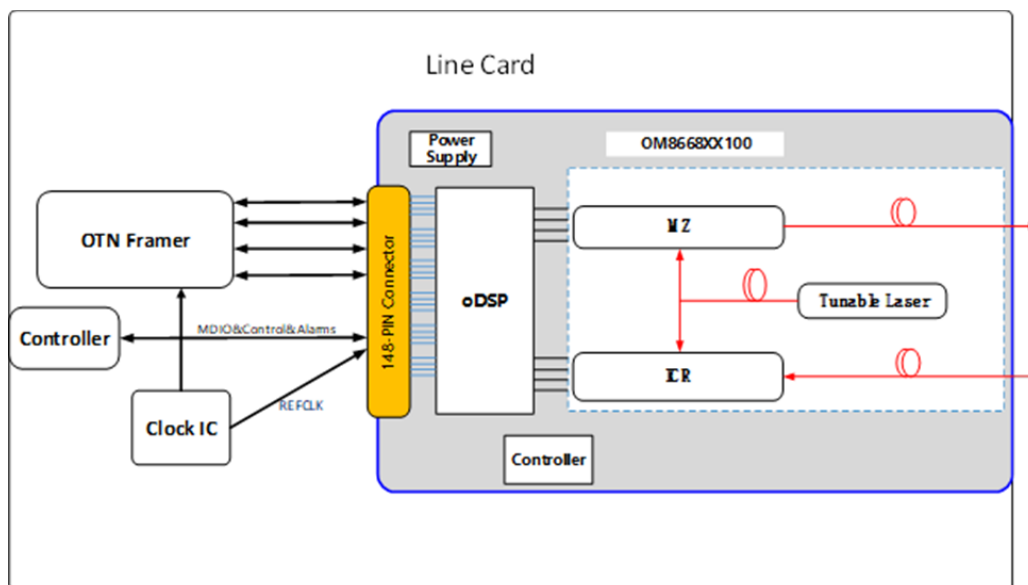
- Transmission reach beyond 1300 km for 200G and 3000 km for 100G over SMF without inline chromatic dispersion compensation
- Hot-pluggable
- Supports PM-DQPSK (100G), PM-QPSK (100G) and PM-16QAM (200G) modulation
- Supports 50 GHz channel spacing
- Supports SD-FEC
- Support OTU4, OTUC2, compliant with OTL4.10/OTL4.4/OTLC2 signaling
- Compliant with CFP MSA CFP Hardware Specification 1.4 with modifications
- Compliant with CFP MSA Management Interface Specification 2.6 with modifications
- Framed PRBS generator/checker on the host and network side interfaces
- SerDes PRBS generator/checker for per lane testing of host interface
- LC optical receptacle
- Operating case temperature: 0°C to 75°C
- Power consumption: 32 W



1. Application

The module is designed to be used on the host board of system integrators to support transmission over DWDM links in Metro/Long-haul networks. As shown in Figure 1-1, it comprises of high-data lanes, a single reference clock for OTUCn hosts, a single 3.3 V power supply, an MDIO interface for module control and status report, and dedicated alarm and control pins.

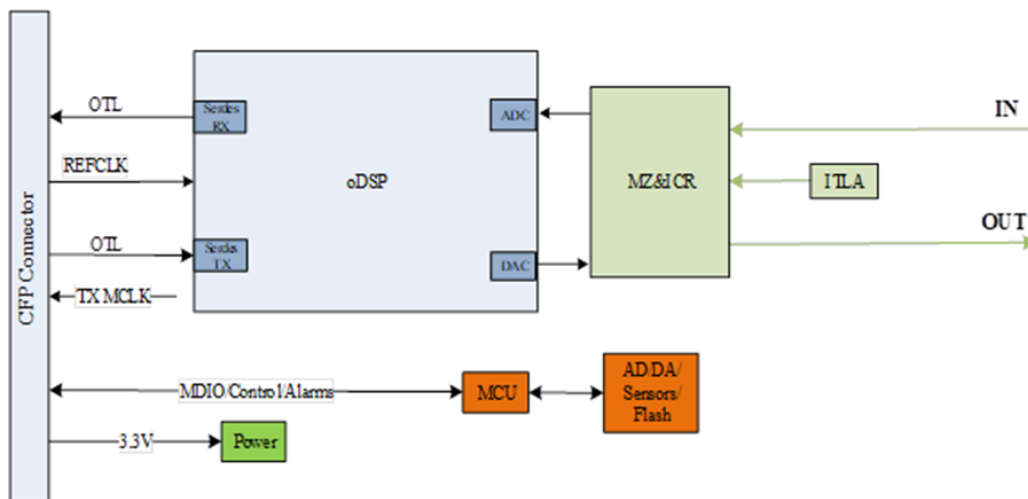
Figure 1-1 200G line card block diagram with OM8668XX100 module



2. Description

The OM8668XX100 module uses a 148-pin OIF MSA connector for all electrical interfaces with the host card, whereas the optical interfaces on the line side are provided through the optical receptacles on the CFP. As depicted in Figure 2-1, the module can be portioned into four parts: oDSP, optical component, control unit and power block.

Figure 2-1 OM8668XX100 module block diagram

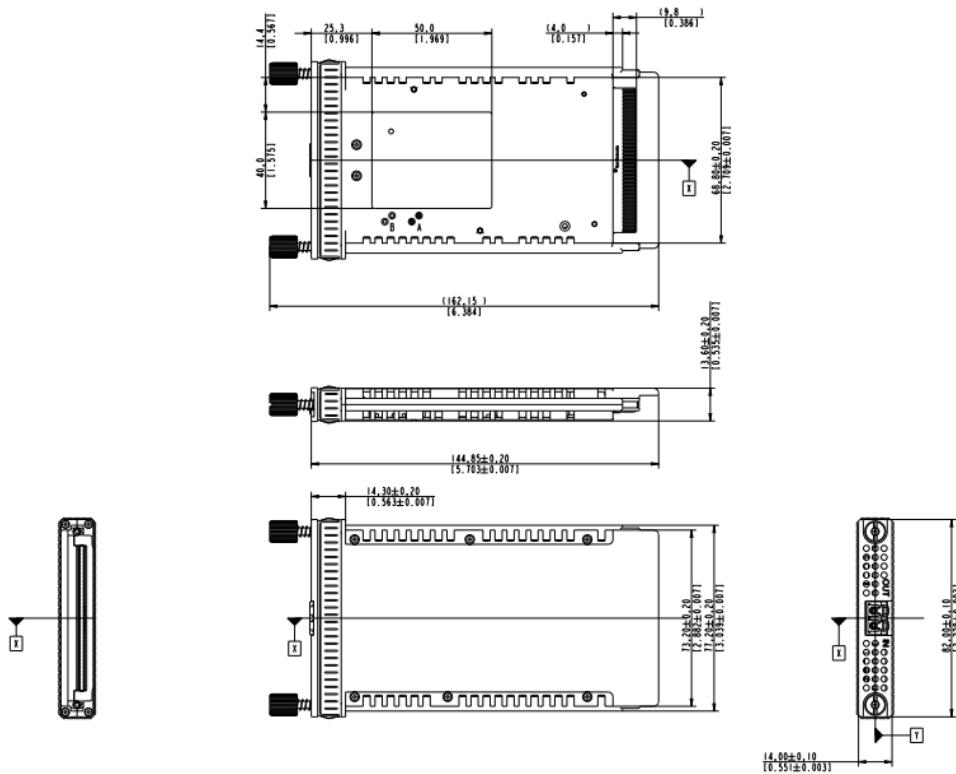


3. Mechanical Specifications

The CFP module is designed to be inserted into a host board with a railing system that includes a heat sink. The module is 144.75 mm x 75.00 mm x 13.60 mm in size and is mechanically compliant with the requirements detailed the CFP Hardware Specification rev.1.4 (with modifications, added heat dissipation holes).

A mechanical model is available from HiSilicon upon request.

Figure 3-1 Mechanical dimensions




4. Ordering Information

Part Number	Description
OM8668XX100	200G/100G, PM-16QAM/PM-DQPSK/PM-QPSK, Coherent CFP

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